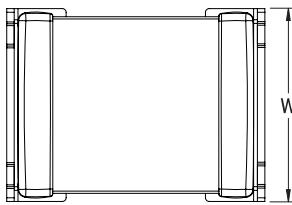
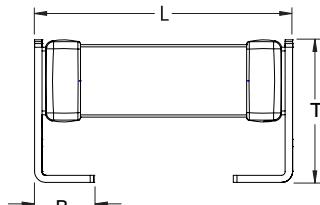


**TOP VIEW**
*Single or Double Chip Stack*

**PROFILE VIEW**
*Single Chip Stack*

[Click here](#) for the 3D model.

**General Information**

Series	KPS SMD Comm X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Single Chip, High Temperature
Features	High Temperature
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	160 mg
Shelf Life	78 Weeks
MSL	1

**Dimensions**

L	3.5mm +/-0.3mm
W	2.6mm +/-0.3mm
T	3.35mm +/-0.10mm
B	0.8mm +/-0.15mm

**Packaging Specifications**

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	600

**Specifications**

Capacitance	0.47 uF
Measurement Condition	1kHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1.0638 GOhms

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